Product Change Notification - KSRA-06BENA698

Date:

04 Jul 2018

Product Category:

Linear Op Amps

Affected CPNs:

Notification subject:

CCB 3054 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 130K wafer technology available in 16L QFN package at NSEB assembly site

Notification text:

PCN Status:

Final notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 130K wafer technology available in 16L QFN package at NSEB assembly site

Pre Change:

Using gold (Au) bond wire and EFTEC-64T lead frame material

Post Change:

Using palladium coated copper with gold flash (CuPdAu) bond wire and C194 lead frame material

Pre and Post Change Summary:

	Pre Change	**Post Change**
Assembly Site	UTAC Thai Limited (UTL-1) LTD. / NSEB	UTAC Thai Limited (UTL-1) LTD. / NSEB
Wire material	Au Wire	CuPdAu Wire
Die attach material	8600	8600
Molding compound material	G700LTD	G700LTD
Lead frame material	EFTEC-64T	C194

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve manufacturability by qualifying CuPdAu bond wire at NSEB assembly site.

Change Implementation Status:

In Progress

Estimated First Ship Date:

August 04, 2018 (date code: 1831)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	August 2017					-->	July2018				August 2018				
Workweek	31	32	33	34	35		27	28	29	30	31	32	33	34	35
Initial PCN Issue Date		X													
Qual Report Availability							X								
Final PCN Issue Date							X								
Estimated Implementation Date											X				

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual Report

Revision History:

August 10, 2017: Issued initial notification.

July 04, 2018: Issued final notification. Attached the Qualification Report. Provided estimated first ship date on August 04, 2018.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

PCN_KSRA-06BENA698_Qual_Report.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to change your product/process change notification (PCN) profile please log on to our website at http://www.microchip.com/PCN sign into myMICROCHIP to open the myMICROCHIP home page, then select a profile option from the left navigation bar.

To opt out of future offer or information emails (other than product change notification emails), click here to go to microchipDIRECT and login, then click on the "My account" link, click on "Update profile" and un-check the box that states "Future offers or information about Microchip's products or services."

Affected Catalog Part Numbers (CPN)

MCP629-E/ML
MCP629T-E/ML
MCP639-E/ML
MCP639T-E/ML
MCP659-E/ML
MCP659T-E/ML
MCP660-E/ML
MCP660T-E/ML
MCP669-E/ML
MCP669T-E/ML